© Copyr	ial Composition right 2005. IPC, Ban onal and Pan-Americ	nockburn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	ibstances v s all lower	vithin the manufactu level materials for v	urer listed i which the r	tem. Note: nanufacture	if the item is an as r has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
upplier Information														
Company name* C			Company unique ID			Unique ID Authority				Respon	Response Date*			
nsemi									2024-05	2024-05-16				
Contact Name Title - Co			tle - Contact			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Authorized Representative* Titl			Title - Representative			Phone - Representative*			Email -	Email - Representative*				
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Produe	Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Iten		Item Number	n Number Mfr Item Name			Effective Date	Version	n Manufacturing Site			Weight*	UOM	Unit Type	
	SZI	SZMMQA5V6T3G SC-74 6 EUT		T SNGL PB FREE		2024-05-16		С	CN1		13.43	mg	Each	
Manufacturing Proccess	Information													
Terminal Plating / Gr	Terminal Plating / Grid Array Material Terminal Base A		Alloy	J-STD-020 MSL Rating Pea			Peak Process Body Temperature Max Time at Peak			k Tempera	Temperature Number of Reflow Cycles			
Matte Tin (Sn) - annealed CU		CU Alloy	lloy 1			260	260 C		30	secor	nds 3			
omments														
vel 1 - maximum time at peal	k temperature durii	ng soldering is 10-3	0 seconds											
or more information regardir	ng material composi	ition please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).				-	_		-
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.67	mg	Supplier	Silicon (Si)	7440-21-3		0.67	mg
Lead Frame	2.55	mg	В	Nickel (Ni)	7440-02-0		0.9664	mg
			Supplier	Iron (Fe)	7439-89-6		1.3362	mg
			Supplier	Copper (Cu)	7440-50-8		0.2473	mg
Mold Compound-Black	10.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		1	mg
			Supplier	Carbon Black (C)	1333-86-4		0.05	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.45	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.5	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1	mg
Plating	0.13	mg	Supplier	Tin (Sn)	7440-31-5		0.13	mg
Wire Bond - Cu	0.08	mg	Supplier	Copper (Cu)	7440-50-8		0.08	mg